

## AMENDMENTS TO THE ABSTRACT:

Page 13, please make the following changes in the abstract:

Abstract:

~~Method for Locating Flaws, and a Marking System~~

~~The present invention relates to a method and a marking system for locating flaws on a three-dimensional object (2), particularly on its surface, the defective points being detected and located using an optical picture-taking device (3,4). To locate a flaw with great accuracy, it is provided that the design data related to the object (2), the optical imaging properties of the picture-taking device (3,4), and the position of the optical picture-taking device (3,4) and the object (2) are known when the picture is taken, and that the location of the flaw on the object (2) is determined and optionally marked. (Figure 1)~~

### **ABSTRACT**

In the method for locating flaws on the surface of a three-dimensional object the flaws are detected and located using one or more optical image-taking device. When a picture is taken showing a flaw the location of the flaw on the object is determined with great accuracy from the design data for the object, the optical imaging properties of the optical image-taking device, and the positions of the optical image-taking device and the object. A marking system for marking the position of the flaws on the object, which are detected by the method, is also described, which includes plural marking heads and displacement devices for positioning and/or activating the marking heads independently of each other.